

# **ASSIGNMENT**

(1-8)	<b>Insert Name(s) of Inventor(s)</b>	(1) <u>Hiroyuki FUJITA</u>	(5) _____
		(2) <u>Hiroto MOCHIZUKI</u>	(6) _____
		(3) _____	(7) _____
		(4) _____	(8) _____

In consideration of the sum of one dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned, each undersigned agrees to assign, and hereby does assign, transfer and set over to

(9)	<b>Insert Name of Assignee</b>	(9) <u>TAIKO DENKI CO., LTD.</u>
(10)	<b>Insert Address of Assignee</b>	(10) <u>7-3, Yaguchi 3-chome, Ota-ku, Tokyo 146-8668 Japan</u>

(hereinafter designated as the Assignee) and Assignee's heirs, successors, assigns and legal representatives, the entire right, title and interest for the United States of America as defined in 35 U.S.C. §100, in the invention, and in all applications for patent including any and all provisional, non-provisional, divisional, continuation, international, confirmation, substitute and reissue application(s), and all Letters Patent, extensions, reissues and reexamination certificates that may be granted on the invention known as

(11)	<b>Insert Identification such as Title, Case Number, or Foreign Application Number</b>	(11) <u>Microconnector and Manufacturing Method of Socket Therefor</u>
		(Attorney Docket No. <u>124053</u> )

for which the undersigned has (have) executed an application for patent in the United States of America on even date herewith or

(12)	<b>Insert Date of Signing of Application</b>	(12) <u>June 20, 2005</u>
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(13)	<b>Alternative Identification for filed applications</b>	(13) U.S. application Serial Number <u>July 1, 2005</u>
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1) Each undersigned agrees to execute all papers necessary in connection with any application and any continuing, divisional or reissue applications for the invention, and any patent(s) issuing thereon, and also to execute separate assignments in connection with such applications and patents as the Assignee may deem necessary.

2) Each undersigned agrees to execute all papers necessary in connection with any interference which may be declared concerning any application or continuation or division thereof, or any patent or reissue application based thereon, for the invention, and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) Each undersigned agrees to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

4) Each undersigned agrees to perform all affirmative acts which may be necessary to obtain, maintain or confirm by reissue or reexamination a grant of a valid United States patent to the Assignee.

5) Each undersigned authorizes and requests the Commissioner of the U.S. Patent and Trademark Office to issue any and all Letters Patents of the United States resulting from said application(s) to the said Assignee, as Assignee of the entire interest, and covenants that he has full right to convey the entire interest herein assigned, and that he has not executed, and will not execute, any agreements in conflict herewith, and agrees that this assignment is binding on him and his heirs, successors, assigns and legal representatives.

6) Each undersigned hereby grants the firm of **OLIFF & BERRIDGE, PLC** the power to insert on this assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

**In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).**

Date	<u>June 20, 2005</u>	Inventor Signature	<u>Hiroki Fujita</u>	(SEAL)
Date	<u>June 20, 2005</u>	Inventor Signature	<u>Hiroto Mochizuki</u>	(SEAL)
Date	_____	Inventor Signature	_____	(SEAL)
Date	_____	Inventor Signature	_____	(SEAL)
Date	_____	Inventor Signature	_____	(SEAL)
Date	_____	Inventor Signature	_____	(SEAL)
Date	_____	Inventor Signature	_____	(SEAL)
Date	_____	Inventor Signature	_____	(SEAL)

This assignment should preferably be signed before: (a) a Notary Public if within the U.S.A. (b) a U.S. Consul if outside the U.S.A. If neither, then it should be signed before at least two witnesses who also sign here:

Date	_____	Witness	_____
Date	_____	Witness	_____

**PATENT APPLICATION**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Hiroyuki FUJITA et al.

Application No.: New U.S. Patent Application

Filed: July 1, 2005

Docket No.: 124053

For: MICROCONNECTOR AND MANUFACTURING METHOD OF SOCKET THEREFOR

**TRANSMITTAL OF POWER OF ATTORNEY AND  
STATEMENT UNDER 37 CFR § 3.73(b)**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Submitted herewith is a Power of Attorney from the Assignee.

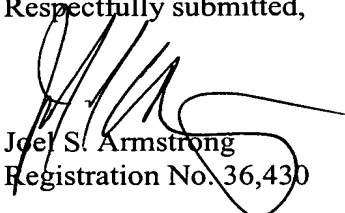
In compliance with 37 CFR §3.73(b), the undersigned hereby states that TAIKO DENKI CO., LTD. is the assignee of the entire right, title and interest in the patent application identified above by virtue of an assignment from the inventors of the patent application identified above. A copy of the assignment is attached hereto.

The undersigned is authorized to act on behalf of the assignee.

In accordance with 37 CFR §1.36(a), submission of this Power of Attorney revokes any powers of attorney previously given.

**ALL CORRESPONDENCE IN CONNECTION WITH THIS APPLICATION SHOULD  
BE SENT TO OLIFF & BERRIDGE, PLC, CUSTOMER NO. 25944, TELEPHONE  
(703) 836-6400.**

Respectfully submitted,

  
Joel S. Armstrong  
Registration No. 36,430

JSA/mps

Date: July 1, 2005

**PATENT APPLICATION**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Hiroyuki FUJITA et al.

Group Art Unit:

Application No.:

Examiner:

Filed:

Docket No.: 124053

For: Microconnector and Manufacturing Method of Socket Therefor

**SPECIFIC POWER OF ATTORNEY**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**TAIKO DENKI CO., LIMITED**, ☒ owner or ☐ co-owner of the entire right, title and interest in the above patent application by virtue of:

- a. ☐ being an inventor, or
- b. ☒ an Assignment
  - i. ☒ copy attached, or
  - ii. ☐ recorded at Reel \_\_\_\_\_, Frame \_\_\_\_\_ of the Patent Office microfilm records,

hereby appoints the patent practitioners associated with Oliff & Berridge, PLC Customer No. 25944 as attorneys of record to prosecute this application and all continuations and divisions thereof, and to transact all business in the Patent and Trademark Office.

The undersigned has reviewed the chain of title and confirms that the aforesaid title is in the owner. The undersigned is authorized to execute this document as or on behalf of the owner.

**ALL CORRESPONDENCE IN CONNECTION WITH THIS APPLICATION  
SHOULD BE SENT TO OLIFF & BERRIDGE, PLC, CUSTOMER NO. 25944,  
TELEPHONE (703) 836-6400.**

June 20, 2005  
Date

  
Signature

Typed Name: Toshihito TAKAHASHI

Title: President  
(if acting on behalf of an Owner)

# DECLARATION UNDER 35 USC §371(c)(4) FOR PCT APPLICATION FOR UNITED STATES PATENT

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below under my name;

I verily believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought, namely the invention entitled: Microconnector and Manufacturing Method of Socket Therefor

described and claimed in international application number PCT/JP2004/000650 filed January 26, 2004.

I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations §1.56.

Under Title 35, U.S. Code §119, the priority benefits of the following foreign application(s) filed by me or my legal representatives or assigns within one year prior to my international application are hereby claimed:

Japanese Patent Application No. 2003-18059 filed January 27, 2003

Japanese Patent Application No. 2003-18060 filed January 27, 2003

The following application(s) for patent or inventor's certificate on this invention were filed in countries foreign to the United States of America either (a) more than one year prior to my international application, or (b) before the filing date of the above-named foreign priority application(s):

ALL CORRESPONDENCE IN CONNECTION WITH THIS APPLICATION SHOULD BE SENT TO OLIFF & BERRIDGE, PLC, CUSTOMER NUMBER 25944, TELEPHONE (703) 836-6400.

I hereby declare that I have reviewed and understand the contents of this Declaration, and that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

1	<b>Typewritten Full Name of Sole or First Inventor:</b>	<u>Hiroyuki</u>	<u>FUJITA</u>
		Given Name	Family Name
2	<b>Inventor's Signature:</b>	<u>Hiroyuki</u>	<u>Fujita</u>
3	<b>Date of Signature:</b>	<u>Jun.</u>	<u>20</u>
		Month	Day
	<b>Residence:</b>	<u>Tokyo</u>	<u>2005</u>
		City	Year
	<b>Citizenship:</b>	<u>Japanese</u>	<u>JAPAN</u>
		Country	
	<b>Post Office Address:</b>	<u>1-9-14, Senkawa, Toshima-ku</u>	
	(Insert complete mailing address, including country)	<u>Tokyo 171-0041 JAPAN</u>	

**Note to Inventor:** Please sign name on line 2 exactly as it appears in line 1 and insert the actual date of signing on line 3.

(Discard this page in a sole inventor application)

1 **Typewritten Full Name  
of Joint Inventor:**

2 **Inventor's Signature:**

3 **Date of Signature:**

Residence:

Citizenship:

Post Office Address:  
(Insert complete mailing  
address, including country)

Hiroto  
Given Name  
Hiroto

Middle Initial

MOCHIZUKI  
Family Name  
Mochizuki

Jun.  
Month

20  
Day

2005  
Year

Tokyo  
City

State or Province

JAPAN  
Country

C/O TAIKO DENKI CO., LIMITED

7-3, Yaguchi 3-chome, Ota-ku, Tokyo 146-8668 JAPAN

1 **Typewritten Full Name  
of Joint Inventor:**

2 **Inventor's Signature:**

3 **Date of Signature:**

Residence:

Citizenship:

Post Office Address:  
(Insert complete mailing  
address, including country)

Given Name

Middle Initial

Family Name

Month

Day

Year

City

State or Province

Country

1 **Typewritten Full Name  
of Joint Inventor:**

2 **Inventor's Signature:**

3 **Date of Signature:**

Residence:

Citizenship:

Post Office Address:  
(Insert complete mailing  
address, including country)

Given Name

Middle Initial

Family Name

Month

Day

Year

City

State or Province

Country

1 **Typewritten Full Name  
of Joint Inventor:**

2 **Inventor's Signature:**

3 **Date of Signature:**

Residence:

Citizenship:

Post Office Address:  
(Insert complete mailing  
address, including country)

Given Name

Middle Initial

Family Name

Month

Day

Year

City

State or Province

Country

**Note to Inventor:** Please sign name on line 2 exactly as it appears in line 1 and insert the actual date of signing on line 3.

**This form may be executed only when attached to the first page of the Declaration and Power of Attorney of the application to which it pertains.**